

<b>Company</b>		<b>DUNS#</b>	<b>URL For Additional Information</b>
National Semiconductor		04-147-2986	<a href="http://www.national.com/analog/quality/green">http://www.national.com/analog/quality/green</a>

<b>Contact</b>	<b>Title</b>	<b>Phone</b>	<b>Email</b>
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<b>Part Number</b>	<b>MSL Rating</b>	<b>Peak Body Temp C</b>	<b>MaxTime(Sec)</b>	<b>Cycles</b>	<b>Unit Type</b>
LMC6462AMJ-QML	1	260	40	4	Each

<b>Document Date</b>	Contains Lead(Pb) - NOT European RoHS NOT China RoHS Compliant.	<b>Weight (mg)</b>	Does NOT Contain Halogens
07-07-2011		1195.68	

### Material Composition Declaration for Electronic Products

Item	Weight (mg)	Component	CAS#	Weight (mg)	Item-ppm	Part-ppm
Ceramic Body	814.001	Al2O3	1344-28-1	720.960	885,700	602,970
		MnO2	1313-13-9	27.432	33,700	22,943
		SiO2	60676-86-0	23.606	29,000	19,743
		TiO2	13463-67-7	15.140	18,600	12,662
		Cr2O3	1308-38-9	11.315	13,900	9,463
		Fe2O3	1309-37-1	9.166	11,260	7,666
		MgO	1309-48-4	4.257	5,230	3,560
		Co3O4	1308-06-1	2.125	2,610	1,777
Seal Glass	229.000	PbO	1317-36-8	118.874	519,100	99,419
		SnO2	18282-10-5	51.227	223,700	42,843
		ZnO	1314-13-2	27.022	118,000	22,600
		B2O3	1303-86-2	18.641	81,400	15,590
		SiO2	60676-86-0	10.694	46,700	8,944
		Al2O3	1344-28-1	2.542	11,100	2,126
Die Attach	2.220	Ag	7440-22-4	1.776	800,000	1,485
		Lead Borate Glass	65997-18-4	0.444	200,000	371
Chip	2.200	Si	7440-21-3	2.187	994,000	1,829
		Al	7429-90-5	0.013	6,000	11
Leadframe	136.000	Fe	7439-89-6	78.880	580,000	65,971
		Ni	7440-02-0	57.120	420,000	47,772
Ext. LeadFinish	12.200	Sn	7440-31-5	7.686	630,000	6,428
		Pb	7439-92-1	4.514	370,000	3,775
Wires	0.061	Al	7429-90-5	0.060	990,000	50
		Si	7440-21-3	0.001	10,000	1

**Note:** The device content disclosed herewith is approximate and is based on engineering estimates only. It has not been verified through analytical testing.

Additionally, the following should be noted:

- One or more dopant materials may be present in the silicon die at sub-ppm levels to provide semiconductor properties.
- Epoxy resin components listed are generic and may or may not be the specific compound used, which is considered proprietary.

RoHS Material Composition Declaration	
<b>RoHS Directive 2002/95/EC</b>	RoHS Definition: Quantity limit of 0.1% by mass (1000 PPM) in homogeneous material for: Lead (Pb), Mercury, Hexavalent Chromium, Polybrominated Biphenyls (PBB), Polybrominated Diphenyl Ethers (PBDE) and quantity limit of 0.01% by mass (100 PPM) of homogeneous material for Cadmium

Subject to the limitations below, National Semiconductor Corporation ("National") certifies the following information as of the document date.

1. National products designated "ROHS Compliant" comply with the European Unions Directive on the Restriction of the Use of Hazardous Substances 2002/95/EC ("RoHS"). Certain National products contain lead in RoHS exempt applications 7a or 7(c)-1.
2. National products do not contain and are not manufactured with ozone depleting compounds.
3. National products do not contain substances identified by the European Chemical Agency ("ECHA") as substances of very high concern ("SVHC") per REACH Regulation (EC) No 1907/2006. National also complies with use restrictions as stipulated in Annex XVII of REACH.
4. National products are manufactured in conformance with National specifications (SC)CSP-9-111C1 Supplier Environmental Requirements for Materials and Products and (SC)CSP-9-111S2 Banned and Reportable Substances.
5. National's list of banned and reportable substances and management system is based on the current version of the Joint Industrial Guide, JIG-101.

National has taken commercially reasonable steps to provide representative and accurate information but may not have independently verified information provided or conducted chemical analysis of incoming materials. Equivalent compliant materials may have been substituted for those stated herein. Material concentrations are the maximum expected concentration of the substance in the device and may not represent the actual concentration. National and its suppliers consider certain limited information to be confidential and thus CAS numbers and other limited information may not be available for release. National's Standard Terms and Conditions of Sale apply to any issue arising out of or in connection with the information provided herein unless otherwise provided by a written contract signed by both parties.

NATIONAL ACCEPTS NO DUTY TO NOTIFY USERS OF THIS DECLARATION OF UPDATES OR CHANGES TO THIS DECLARATION.



John L. Conn  
Vice President Quality

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Vice President Quality

**Banned Substance Monitoring**

<b>Part Number</b>	<b>Document Date</b>
LMC6462AMJ-QML	07-07-2011

Contains Lead(Pb) - NOT European RoHS Compliant.

NOT China RoHS Compliant.

<b>Item#</b>	<b>Material</b>	<b>Cd</b>	<b>CrVI</b>	<b>Pb</b>	<b>Hg</b>	<b>PBB</b>	<b>PBDE</b>	<b>Cl</b>	<b>Br</b>	<b>Ref#</b>
1	CHIP	<1	<1	<1	<30	<10	<10	<75	<50	1000
2	EXTLF	<2	N/D	367077	<2	<5	<5	<50	<50	57
3	FRAME	<2	N/D	<2	<2	<5	<5	N/A	N/A	52
4	PASTE	<2	<2	<2	<2	<5	<5	<50	<50	150
5	WIRE	<2	N/D	<2	<2	<5	<5	N/A	N/A	604

\* Cd: Cadmium, CrVI: Hexavalent Chromium, Pb: Lead, Hg: Mercury, NA: Not Applicable

\* Unless otherwise noted, units are in PPM (parts-per-million)

<b>Ref#</b>	<b>3rd Party Analysis</b> (available upon request, subject to a non-disclosure agreement)
1000	Analysis on 01/24/2011 by Balazs as per Report# 11-00322-00
57	Analysis on 04/29/2011 by SGS per Report# LPCI/04327(B)/11
52	Analysis on 04/29/2011 by SGS per Report# LPCI/04324(B)/11
150	Analysis on 04/29/2011 by SGS per Report# LPCI/04437(B)/11
604	Analysis on 04/29/2011 by SGS per Report# LPCI/04451(B)/11

部件名称 Part	有毒有害物质或元素 Toxic and harmful substances or elements					
	铅 (Pb)	汞 (Hg)	镉 (Cd)	六价铬 (Cr6+)	多溴联苯 (PBB)	多溴二苯醚 (PBDE)
集成电路 Integrated Circuit	X	○	○	○	○	○

**○** : 表示该有毒有害物质在该部件所有均质材料中的含量均在SJ/T 11363-2006标准规定的限量要求以下。

**○** : Indicates that this hazardous substance contained in all homogeneous materials of this part is below the limit requirement in SJ/T 11363-2006.

**X** : 表示该有毒有害物质至少在该部件的某一均质材料中的含量超出SJ/T 11363-2006标准规定的限量要求。

**X** : Indicates that this hazardous substance contained in at least one of the homogeneous materials of this part is above the limit requirement in SJ/T 11363-2006.

**美国国家半导体的产品不会含有镉、汞、六价铬、多溴联苯(PBB)和二苯醚(PBDE)。**

National Semiconductor's products will not contain cadmium, mercury, hexavalent chromium, polybrominated biphenyls (PBBs) and diphenyl ether (PBDE).



**环保使用期限(epup)** 是指以符号在这里展出. 环保使用期限(epup)的有效期只有当产品使用范围以内的数据表中的规格.

The Environmental Protection Use Period (EPUP) is defined by the symbol shown here. The Environmental Protection Use Period (EPUP) is valid only when product is used within the limits of the data sheet specifications.